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PMP11114 REV A Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
C1, C17, C20, C23	4	0.1uF	Std	Std	CAP, CERM, 0.1 µF, 50 V, +/- 10%, X7R, 0402	0402
C2, C3, C4	3	10uF	Std	Std	CAP, CERM, 10 µF, 50 V, +/- 10%, X7R, 1210	1210
C5, C6	2	4.7uF	Std	Std	CAP, CERM, 4.7 µF, 50 V, +/- 10%, X7R, 1206	1206
C7, C16	2	0.47uF	Std	Std	CAP, CERM, 0.47 µF, 16 V, +/- 10%, X7R, 0603	0603
C8	1	22pF	Std	Std	CAP, CERM, 22 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C9	1	4700pF	Std	Std	CAP, CERM, 4700 pF, 50 V, +/- 10%, X7R, 0402	0402
C10, C15, C21	3	1000pF	Std	Std	CAP, CERM, 1000 pF, 50 V, +/- 10%, X7R, 0402	0402
C11, C12	2	22uF	Std	Std	CAP, CERM, 22 µF, 16 V, +/- 10%, X7R, 1210	1210
C13	1	220uF	10TPE220ML	Panasonic	CAP, Polymer, 220 µF, 10 V, +/- 20%, 0.025 ohm, 7.3x2.8x4.3mm SMD	7.3x2.8x4.3mm
C14	1	Open	Std	Std	CAP, CERM, 2200 pF, 25 V, +/- 10%, X7R, 0402	0402
C18	1	1uF	Std	Std	CAP, CERM, 1 µF, 50 V, +/- 10%, X7R, 0805	0805
C19	1	10pF	Std	Std	CAP, CERM, 10 pF, 50 V, +/- 5%, C0G/NP0, 0402	0402
C22	1	1uF	Std	Std	CAP, CERM, 1 µF, 10 V, +/- 10%, X7R, 0603	0603
C24, C25, C26, C27, C28, C29	6	10uF	Std	Std	CAP, CERM, 10 µF, 35 V, +/- 20%, X5R, 0603	0603
D1	1	60V	MBR0560-TP	Micro Commercial Component	Diode, Schottky, 60 V, 3 A, SOD-123	SOD-123
D2	1	15V	BZT52C15T-7	Diodes Inc.	Diode, Zener, 15 V, 300 mW, SOD-523	SOD-523
D3	1	39V	SM6T39CA	STMicroelectronics	Diode, TVS, Bi, 39 V, 600 W, SMB	SMB
J1	1		39357-0002	Molex	Terminal Block, 3.5 mm, 2x1, Tin, TH	Terminal Block, 3.5 mm, 2x1, TH
J2, J3	2		1070-MS21-0048-X3	Luxshare-ICT	USB 2.0 Type-C Receptacle	1070-MS21-0048
L1	1	470nH	SPM6530T-R47M170	TDK	Inductor, Shielded, Ferrite, 470 nH, 15.7 A, 0.0036 ohm, SMD	SMD 7.1x3.0x6.5mm
L2	1	6.8uH	VLF12060T-6R8	TDK	Inductor, Shielded, Ferrite, 6.8 µH, 7.5 A, 0.013 ohm, SMD	Inductor, 12.8x6x12.5mm
Q1	1	-40V	TPCA8107	Toshiba	MOSFET, P-CH, -40 V, 24mohm	PowerPAK_SO-8L
Q2, Q3	2	60V	CSD18537NQ5A	Texas Instruments	MOSFET, N-CH, 60 V, 50 A, SON 5x6mm	SON 5x6mm
R1, R3	2	0	Std	Std	RES, 0, 5%, 0.063 W, 0402	0402
R2	1	1.00Meg	Std	Std	RES, 1.00 M, 1%, 0.063 W, 0402	0402
R4, R7	2	3.32	Std	Std	RES, 3.32, 1%, 0.063 W, 0402	0402
R5	1	39.2k	Std	Std	RES, 39.2 k, 1%, 0.063 W, 0402	0402
R6, R8, R22, R23, R24, R25, R26, R27, R29, R30, R31, R32, R33, R34, R35, R37	16	100k	Std	Std	RES, 100 k, 1%, 0.063 W, 0402	0402
R9	1	49.9	Std	Std	RES, 49.9, 1%, 0.063 W, 0402	0402
R10	1	68.1k	Std	Std	RES, 68.1 k, 1%, 0.063 W, 0402	0402
R11	1	1.82k	Std	Std	RES, 1.82 k, 1%, 0.063 W, 0402	0402
R12	1	1.00k	Std	Std	RES, 1.00 k, 1%, 0.063 W, 0402	0402
R13, R18, R19	3	10.0	Std	Std	RES, 10.0, 1%, 0.1 W, 0603	0603
R14	1	10.5k	Std	Std	RES, 10.5 k, 1%, 0.063 W, 0402	0402
R15	1	13.0k	Std	Std	RES, 13.0 k, 1%, 0.063 W, 0402	0402
R16	1	0.01	Std	Std	RES, 0.01, 1%, 1 W, 2010	2010
R17	1	464	Std	Std	RES, 464, 1%, 0.063 W, 0402	0402
R20	1	19.6k	Std	Std	RES, 19.6 k, 1%, 0.063 W, 0402	0402
R21	1	3.74k	Std	Std	RES, 3.74 k, 1%, 0.063 W, 0402	0402
R28, R36	2	10.0k	Std	Std	RES, 10.0 k, 0.1%, 0.063 W, 0402	0402

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
TP1, TP2	2	Red	5000	Keystone	Test Point, Miniature, Red, TH	Red Miniature Testpoint
TP3	1	Black	5001	Keystone	Test Point, Miniature, Black, TH	Black Miniature Testpoint
U1	1		LM25117PSQ/NOPB	Texas Instruments	Wide Input Range Synchronous Buck Controller with Analog Current Monitor, RTW0024A	RTW0024A
U2	1		TPS2513DBV	Texas Instruments	USB Dedicated Charging Port Controller, DBV0006A	DBV0006A
U3, U4	2		TPS25810RVC	Texas Instruments	USB Type-C DFP Controller and Power Switch with Load Detection, RVC0020A	RVC0020A

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